

CLAIM AMENDMENTS

1. (Currently Amended) A metal electrode ~~built~~ on a wire, which is ~~formed~~ located on a substrate, said metal electrode comprising multiple metallic layers including at least a first layer and a second layer lying, from an outermost surface of said metal electrode toward the substrate, in this order, wherein the first layer contains tin as a principal constituent, the second layer contains a metallic element which produces an eutectic reaction with tin, and the melting point of the first layer is higher than ~~that~~ the melting point of the second layer.

2. (Original) The metal electrode according to claim 1, wherein the metallic element which produces the eutectic reaction with tin is indium.

3. (Currently Amended) The metal electrode according to claim 1, wherein the temperature at which the metallic element of the second layer produces the eutectic reaction with tin is ~~equal to or lower~~ no higher than 221°C.

4. (Currently Amended) The metal electrode according to claim 1, wherein the wire contains aluminum as a principal constituent, and the metallic layers of said metal electrode further ~~includes~~ include a third layer containing copper as a principal constituent, a fourth layer containing gold as a principal constituent, and a fifth layer containing nickel as a principal constituent, lying in this order ~~toward~~ in the direction of the substrate, between the second layer and the wire.

5. (Currently Amended) The metal electrode according to claim 4, wherein the first ~~to, second, third, fourth, and~~ fifth metallic layers are formed by electroless plating ~~processes~~.

6. (Currently Amended) A method of joining a metal electrode ~~built~~ on a wire, which is ~~formed~~ located on a substrate, to a circuit card ~~of which joint~~ having a joining surface ~~is formed~~ of a material which diffuses into tin when heated, said metal electrode comprising multiple metallic layers including at least a first layer and a second layer lying, from an outermost surface of said metal electrode toward the substrate, in this order, wherein the first layer contains tin as a principal constituent, the second layer contains a metallic element which produces an eutectic reaction with tin, and the melting point of the first layer is higher than ~~that~~ the melting point of the second layer, ~~and said method comprising the steps of:~~
bringing said metal electrode ~~in~~ into contact with the ~~joint~~ joining surface of said

circuit card; and

heating said metal electrode ~~at~~ to a temperature at least equal to ~~or higher than~~ the lowest one of temperatures at which a eutectic reaction occurs between the first and second layers, but lower than the melting point of the first layer.